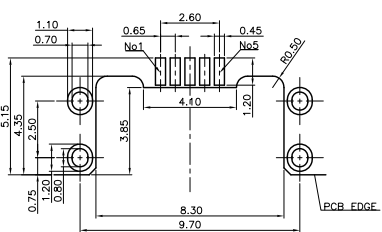
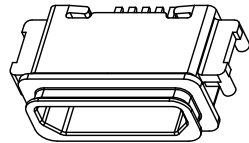
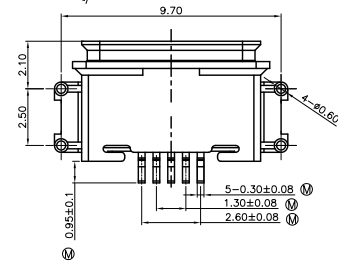
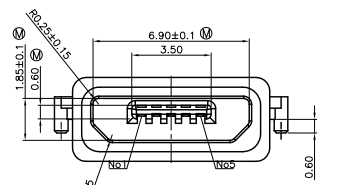


NOTES:

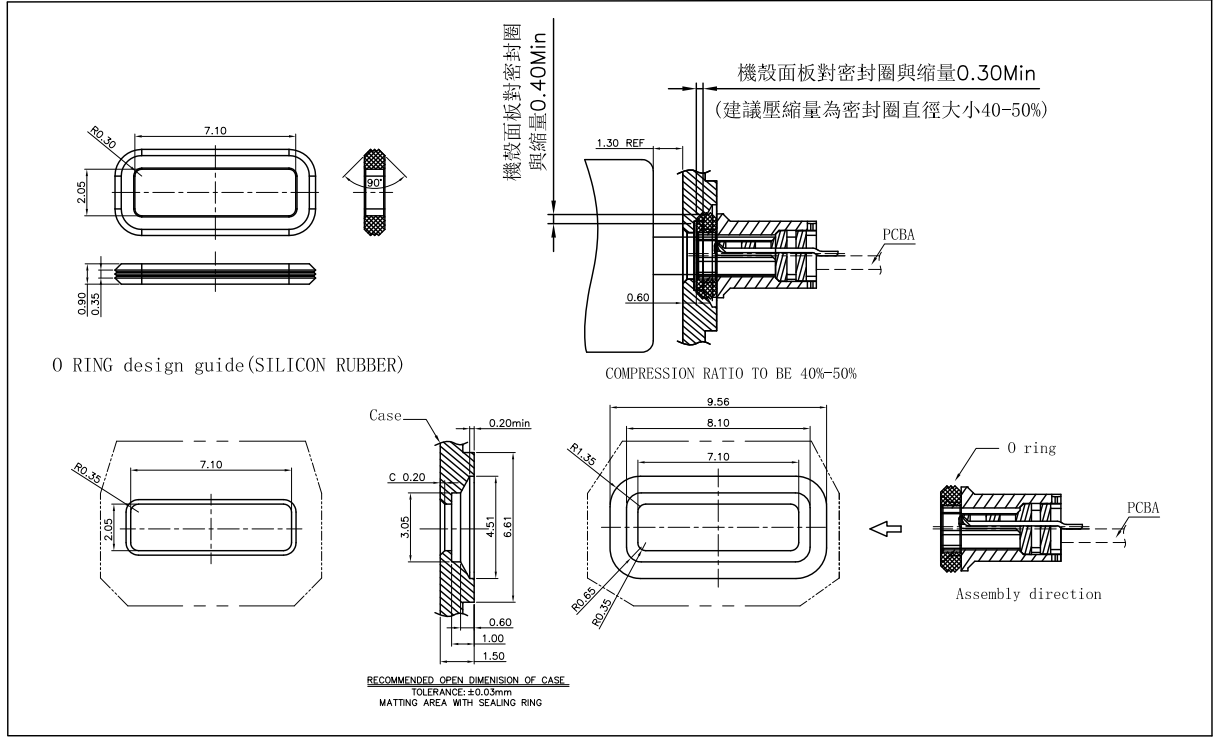
- MATERIAL:  
HOUSING: THERMOPLASTIC HIGH-TEMP UL94V-0 BLACK COLOR.  
CONTACT: COPPER ALLOY.  
SHELL: STAINLESS STEEL.
- FINISH:  
2.1. TERMINAL CONTACT: (SEE TAB) GOLD PLATING ALL OVER 50u"  
Min NICKEL AND GOLD PLATING G/F ALL OVER 50u" Min NICKEL ON  
SOLDER AREA  
2.2. OUT SHELL: 50u" Min. NICKEL ALL OVER
- APPLIED TO IR SOLDERING PROCESS.

4. SPECIFICATION:

- ELECTRICAL CHARACTERISTICS  
CONTACT CURRENT RATING: Signal pin 1A, Power pin 1.8A  
VOLTAGE RATING: 30V AC rms.  
CONTACT RESISTANCE: 30mΩ MAX.  
DIELECTRIC WITHSTANDING VOLTAGE:  
UNMATEP CONTACT 100V AC rms, 60MHZ FOR 1 MINUTE.  
INSULATION RESISTANCE: 1000MΩ MIN. 100V DC  
TEMPERATURE RANGE: -30°C TO +85°C
- MECHANICAL:  
INSERTION FORCE: 35N MAX.  
WITHDRAWAL FORCE: 8N MIN, 25N MAX.



RECOMMENDED PCB LAYOUT  
TOLERANCE: ±0.03mm  
RECOMMEND PCB THICKNESS: 0.60mm



Champyang International Ltd., Co

A0	RELEASED	Allen	2019-07-29
REV	DESCRIPTION.	APPD.	Date

FILE NO : AMU03 ( Series)		TITLE 圖名		MICRO USB2.0 WATERPROOF SINK		UNIT 單位	mm inch
TOLERANCE(公差): 0.000 mm ± 0.075 mm 0.00 mm ± 0.15 mm 0.0 mm ± 0.25 mm		PART NO. 料號		AMU03-0105-xx1-S13-WP-A-S		SCALE 比例	1:1
		DRAWN BY 製圖		Ben	DATE 日期	2019-07-29	REV. 版本
		CHECKED BY 審核		Allen	DATE 日期	2019-07-29	⊕